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ABSTRACT

The invention relates to a method of bonding a polymer surface to an electrically conductive or semiconductive surface, which method is characterized in that it comprises:

- a) the electrografting of an organic film onto the conductive or semiconductive surface; and then
- b) an operation of bonding the polymer surface to the conductive or semiconductive surface thus grafted.

It also relates to applications of this method and to structures obtained by its implementation.

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